

ABSTRACT OF THE DISCLOSURE

Electrodes of one face of a semiconductor, which has electrodes formed on both faces, and a heat radiating plate are directly joined to quickly absorb and
5 diffuse heat of the semiconductor, thereby improving a heat radiation effect. At the same time, electrodes on an opposite face of the semiconductor are connected to projecting electrodes that are thicker than a wire for wire bonding and larger in current capacity. These projecting electrodes can accordingly be utilized as
10 connecting terminals to a circuit board. Ceramic is used for the heat radiating plate, so that semiconductors of different functions can be mounted simultaneously.